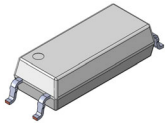


# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

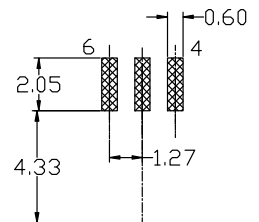
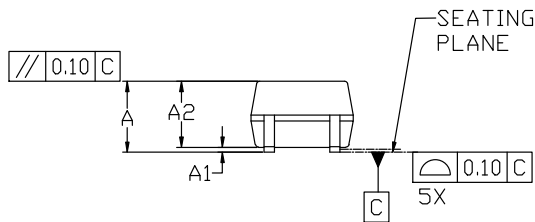
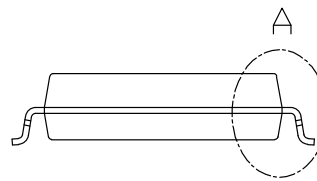
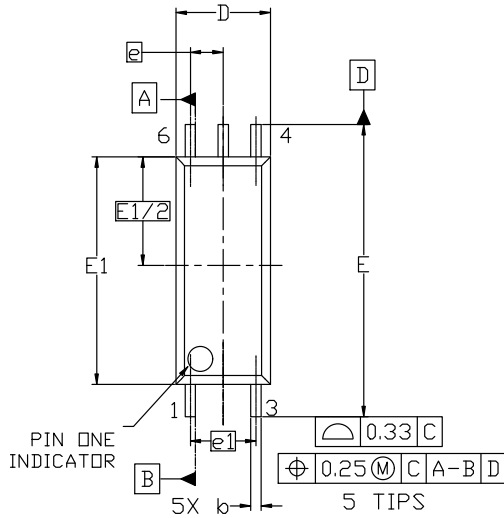


**SOIC5 (6) 3.65x8.80x2.55, 1.27P**  
CASE 752AG  
ISSUE B

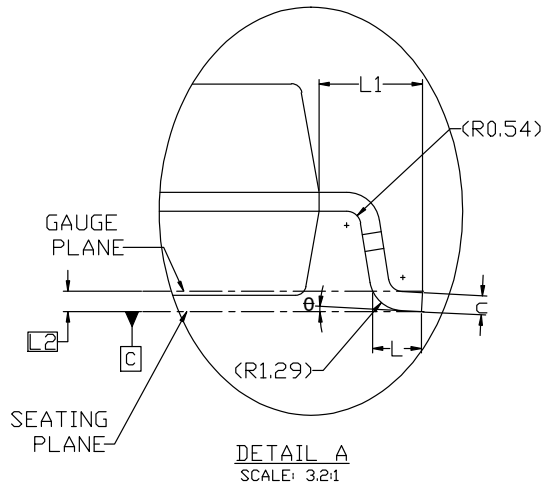
DATE 24 JUL 2023

NOTES: UNLESS OTHERWISE SPECIFIED

- A) THIS PACKAGE DOES NOT CONFORM TO ANY STANDARD.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS
- D) DRAWING CONFORMS TO ASME Y14.5M-1994



DIM	MILLIMETER		
	MIN.	NOM.	MAX.
A	--	--	2.95
A1	0.10	0.20	0.30
A2	2.45	2.55	2.65
b	0.31	0.41	0.51
c	0.19	0.22	0.25
D	3.55	3.65	3.75
E	11.20	11.30	11.40
E1	8.70	8.80	8.90
E1/2	4.20 BSC		
e	1.27 BSC		
e1	2.54 BSC		
L	0.44	0.59	0.74
L1	1.15	1.25	1.35
L2	0.25 BSC		
θ	0°	--	8°



LAND PATTERN  
RECOMMENDATION

\*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

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<b>DESCRIPTION:</b>	<b>SOIC5 (6) 3.65x8.80x2.55, 1.27P</b>	<b>PAGE 1 OF 1</b>

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